## Amendments to the Claims

1. (Currently Amended) <u>An apparatus</u> for detecting wafer flat shift, comprising:

a plurality of sensors and a relay eireuit for operating a solenoid in a power supply circuit for shutting off wafer fabrication equipment, the sensors <u>for</u> detecting a shift in wafer flat position; and the power supply circuit <u>for</u> shutting off the wafer fabrication equipment; <u>wherein the relay receives signals from the sensors and the solenoid operated by the relay to open at least one door of the wafer fabrication equipment to release a <u>corresponding wafer for further processing</u>; and a wafer flat shift shutting off at least one of the signals from the sensors.</u>

- 2. (Currently amended) The apparatus of claim 1, further comprising: wherein the sensors being adjusted to detect a wafer flat shift in a plurality of directions of angular displacement.
- 3. (Currently amended) The apparatus of claim 1, further comprising: wherein the sensors being adjusted to detect a wafer flat shift in a range of  $(2)(0.9^0)$  to  $(5)(0.9^0)$  angular displacement.
- 4. (Currently amended) The apparatus of claim 1, further comprising:

   a frame; and
   an adjustable mounting mechanism mounting each of the sensors on the frame for

   adjustment along <u>substantially</u> orthogonal axes.
- 5. (Previously Presented) The apparatus of claim 1, further comprising: a frame; and

the sensors being adjustably mounted on the frame.

- 6. (Cancelled.)
- 7. (Currently Amended) A method of detecting wafer flat shift comprising the steps of: [[;]]

detecting a wafer flat shift by an optical beam sensor, sending a signal from the sensors to a solenoid through a relay; and

operating the solenoid by the relay to open at least one door of the wafer
fabrication equipment to release a corresponding wafer for further processing;
shutting off at least one of the signals from the sensors by the wafer flat shift; and shutting off a wafer fabrication equipment when the wafer flat shift exceeds a set amount.

- 8. (Previously Presented) The method as recited in claim 7, further comprising the step of:

  detecting a wafer flat shift in a plurality of directions of angular displacement.
- 9. (Previously Presented) The method as recited in claim 7, further comprising the step of:
  detecting the wafer flat shift by optical beam sensors.
- 10. (Previously Presented) The method as recited in claim 7, further comprising the step of:

detecting a wafer flat shift in a range of  $(2)(0.9^{\circ})$  to  $(5)(0.9^{\circ})$  angular displacement.

11. (Previously Presented) The method as recited in claim 7, further comprising the

steps of:

detecting the wafer flat shift by optical beam sensors; and adjusting the positions of the sensors.

- 12. (Cancelled.)
- 13. (Currently Amended) The method as recited in elaim 12 claim 7, further comprising the step of:

detecting a wafer flat shift of  $(2)(0.9^0)$  angular displacement.

14. (Previously Presented) The method as recited in elaim 12 claim 7, further comprising the step of:

detecting a wafer flat shift of (5)(0.9°) angular displacement.

15. (Currently Amended) A control circuit, comprising:

sensors to detect an edge of a wafer flat on a wafer;

a power supply supplying power to the sensors;

a relay activated by outputs of the sensors;

a solenoid activated by the relay to unlock a door for exit of the wafer to equipment for further wafer fabrication; and

at least one of the sensors sensing a wafer flat shift, which shuts off the equipment.

- 16. (Previously Presented) The control circuit of claim 15, further comprising: the sensors being set to detect a wafer flat shift of (2)(0.9°) angular displacement.
- 17. (Previously Presented) The control circuit of claim 15, further comprising: the sensors being set to detect a wafer flat shift of (5)(0.9°) angular displacement.

- 18. (Previously Presented) The control circuit of claim 15, further comprising: the sensors being mounted for adjustment along orthogonal axes corresponding to the a wafer flat shift in angular displacement.
- 19. (Previously Presented) The control circuit of claim 15, further comprising: the sensors being adjustable on the frame.
- 20. (Previously Presented) The control circuit of claim 15, further comprising: the sensors being adjustable along orthogonal axes.